PCB Layer Stack Manager for AP Reference Design Solution
(2 Layer)

Top Layer →

Total Thickness: 63±4mil

Bottom Layer →

FR4 Core 60 mil (ε r=4.2 ~4.6)

Top Soldermask(0.5mil)
3u Chemical Gold/Ni
1 OZ(1.4mil) Copper

3u Chemical Gold/Ni
1 OZ(1.4mil) Copper
Bottom Soldermask(0.5mil)

Total Layer: 2

Note: 50±5 ohm impedance's Line Width: 20 mil and Line Gap:5 mil
for Top layer to Bottom layer.